Integrated Circuit Systems, Inc.

ICS9212-01

Preliminary Product Preview

Direct Rambus™ Clock Generator

General Description

The **ICS9212-01** is a High-speed clock generator providing 400 MHz differential clock source for direct Rambus™ memory system. It includes DDLL (Distributed Delay locked loop) and phase detection mechanism to synchronize the direct Rambus™ channel clock to an external system clock. **ICS9212-01** provides a solution for a broad range of Direct Rambus memory applications. The device works in conjunction with the ICS9250-09.

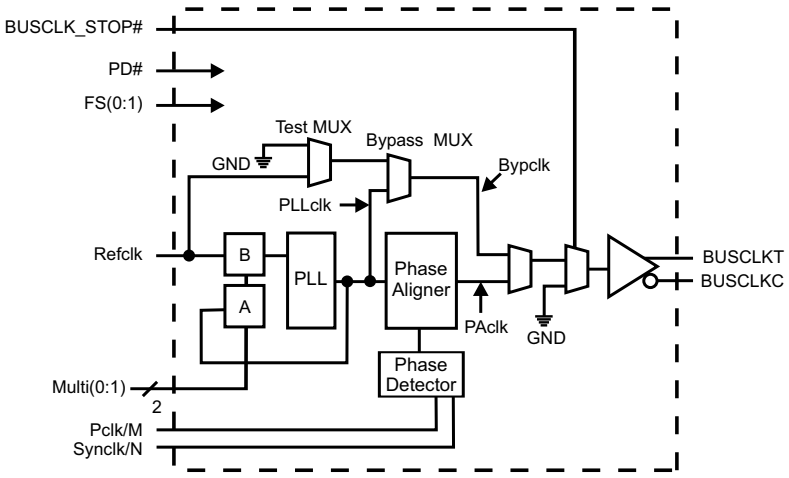
The **ICS9212-01** power management support system turns "off" the Rambus™ channel clock to minimize power consumption for mobile and other power –sensitive applications. In "clock off" mode the device remains "on" while the output is disabled, allowing fast transitions between clock-off and clock –on states. In "power down" mode it completely powers down for minimum power dissipation.

The **ICS9212-01** meets the requirements for input frequency tracking when the input frequency clock is using Spread Spectrum clocking and also the optimum bandwidth is maintained while attenuating the jitter of the reference signal.

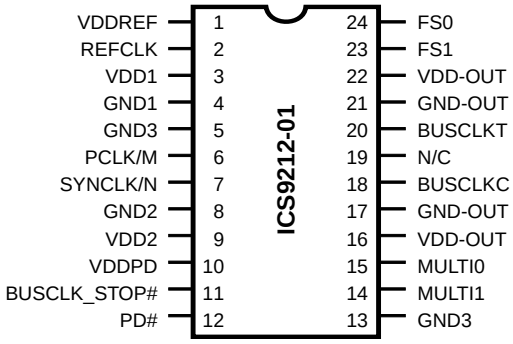
Features

- Compatible with all Direct Rambus™ based IC s
- Up to 400 MHz differential clock source for direct Rambus™ memory system
- Cycle to cycle jitter is less than 50ps
- 3.3 ± 5% supply
- Synchronization flexibility: Supports Systems that need clock domains of Rambus channel to synchronize with system or processor clock, or systems that do not require synchronization of the Rambus clock to another system clock
- Excellent power management support
- REFCLK input is from the ICS9250-09.

Block Diagram



Pin Configuration



24-Pin 150 Mil SSOP

Pin Descriptions

Pin #	Name	Type	Description
1	VDDREF	REFV	Reference voltage for refclk, to be connected to CK133
2	REFCLK	IN	Reference clock, to be connected to CK133
3	VDD1	PWR	3.3 V power supply used for PLL
4	GND1	PWR	Ground for PLL
5, 13	GND3	PWR	Ground for control inputs
6,7	PCLK/M, SYNCLK/N	IN	Phase controller input, used to drive a phase aligner that adjusts the phase of the busclk.
8	GND2	PWR	Ground for phase aligner
9	VDD2	PWR	3.3 V power supply used for phase aligner
10	VDDPD	REFV	Reference voltage for phase detector inputs connected to the controller
11	BUSCLK_ STOP#	IN	Active low output enable/disable
12	PD#	IN	3.3V CMOS active low power down, the device is powered down when the "(PD#) =0"
14,15	MULTI (0:1)	IN	3.3V CMOS PLL Multiplier select, logic for selecting the multiply ratio for the PLL from the input REFCLK
16	VDD_OUT	PWR	3.3V supply for clock out puts
17	GND_OUT	PWR	Ground for clock outputs
18	BUSCLKC	OUT	Out put clock connected to the Rambus channel. This output is the complement of BUSCLK
19	N/C	N/C	NOT USED
20	BUSCLKT	OUT	Out put clock connected to the Rambus channel. This output is the true component of BUSCLK
21	GND_OUT	PWR	Ground for clock outputs
22	VDD_OUT	PWR	3.3V supply for clock out puts
24, 23	FS(0:1)	IN	3.3V CMOS Mode control, used in selecting bypass, test, normal, and output test (OE)

PLL DIVIDER SELECTION AND PLL VALUES (PLLCLK = REFCLK*A/B)

Mult0	Mult1	A	B	PLLCLK for REFCLK=50MHz	PLLCLK for REFCLK=66.67MHz
0	0	4	1	200.00	266.68
0	1	6	1	300.00	400.02
1	1	8	1	400.00	533.36
1	0	8	3	133.33	177.79

BYPASS AND TEST MODE SELECTION

Mode	FS0	FS1	Bypclk (int.)	BusClk	BusClkB
Normal	0	0	Gnd	PAclk	PAclkB
Bypass	1	0	PLLclk	PLLclk	PLLclkB
Test	1	1	Refclk	Refclk	RefclkB

POWER MANAGEMENT MODES

State	PwrDnB	StopB
NORMAL	1	1
Clk Off	1	0
Powerdown	0	X

Absolute Maximum Ratings

Supply Voltage ..... 4.0 V
Logic Inputs ..... GND –0.5 V to V_{DD} +0.5 V
Ambient Operating Temperature ..... 0°C to +70°C
Storage Temperature ..... –65°C to +150°C

Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only and functional operation of the device at these or any other conditions above those listed in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Electrical Characteristics-input/supply/Outputs

Parameters	Symbol	Min	Max	Unit
Supply Voltage	VDD	3.15	3.45	V
Refclk Input cycle time	$t_{CYCLE,IN}$	10	40	ns
Input cycle-to-cycle Jitter	$t_{J,IN}$	-	250	ps
Input Duty cycle over 10k cycles	DC_{IN}	40%	60%	t_{CYCLE}
Input frequency of modulation	$F_{m,in}$	30	33	KHz
Modulation index	$P_{M,IN}$	0.25	0.5	%
Phase detector input cycle time at PDclk/M & Synclk/N	$t_{CYCLE,PD}$	30	100	ns
Initial phase error at phase detector inputs	$T_{err,init}$	-0.5	0.5	$t_{CYCLE,PD}$
Phase detector input duty cycle over 10k cycles	$D_{CIN,PD}$	25%	75%	$t_{CYCLE,PD}$
Input rise & fall times (measured at 20%-80% of input voltage) for PDCLK/M & SYNCLK/N,&REfCLK	T_{IR},T_{IF}	-	1	ns
Input capacitance at PDCLK/M,Synclk/N,&REFCLK	$C_{IN,PD}$	-	7	pF
Input Capacitance matching at PCLK/M & SYNCLK/N	$\Delta C_{IN,PD}$	-	0.5	pF
Input capacitance at CMOS pins	$C_{IN,CMOS}$	-	10	pF
Input (CMOS) signal low voltage	V_{IL}	-	0.3	Vdd
Input (CMOS) signal high voltage	V_{IH}	0.7	-	Vdd
REFCLK input low voltage	$V_{IL,R}$	-	0.3	Vddi,R
REFCLK input high voltage	$V_{IH,R}$	0.7	-	Vddi,R
Input signal low voltage for PD inputs and STOP	$V_{IL,PD}$	-	0.3	Vddi,PD
Input signal high voltage for PD inputs and STOP	$V_{IH,PD}$	0.7	-	Vddi,PD
Input supply referance for REFCLK	$V_{DD,IR}$	1.3	3.3	V
Input supply referance vfor PD inputs	$V_{DDI,PD}$	1.3	3.3	V
Phase detector phase error for distributed loop measured at PDCLK/M & SYNCLK/N(rising	$t_{ERR,PD}$	-100	100	ps
Cycle cycle time	t_{CYCLE}	2.5	3.75	ns
Cycle-to-cycle jitter at Busclk/BUSCLKB	t_J	-	50	ps
Total jitter over 2,3, or 4clock cycles	tJ	-	100	ps
Phase aligner, phase step size (BSCLK/BUSCLKB)	t_{STEP}	1	-	ps
PLL out put phase error when tracking SSC	$t_{ERR,SSC}$	-100	100	ps
Out put crossing-point voltage	V_X	1.3	1.8	V
Output voltage swing	V_{COS}	0.4	0.6	V
Output high voltage	V_H	-	2	V
Out put duty cycle over 10k cycle	DC	40%	60%	t_{CYCLE}
Output cycle -to-cycle duty cycle error	$t_{DC,ERR}$	-	50	ps
Output rise & fall times (measured at 20%-80% of output voltage)	t_{CR},t_{CF}	300	500	psd
Difference between rise and fall times on a single device(20%-80%)	$t_{CR,CF}$	-	100	ps

General Layout Precautions:

1) Use a ground plane on the top layer of the PCB in all areas not used by traces.

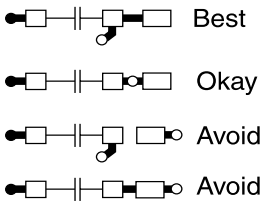
2) Make all power traces and vias as wide as possible to lower inductance.

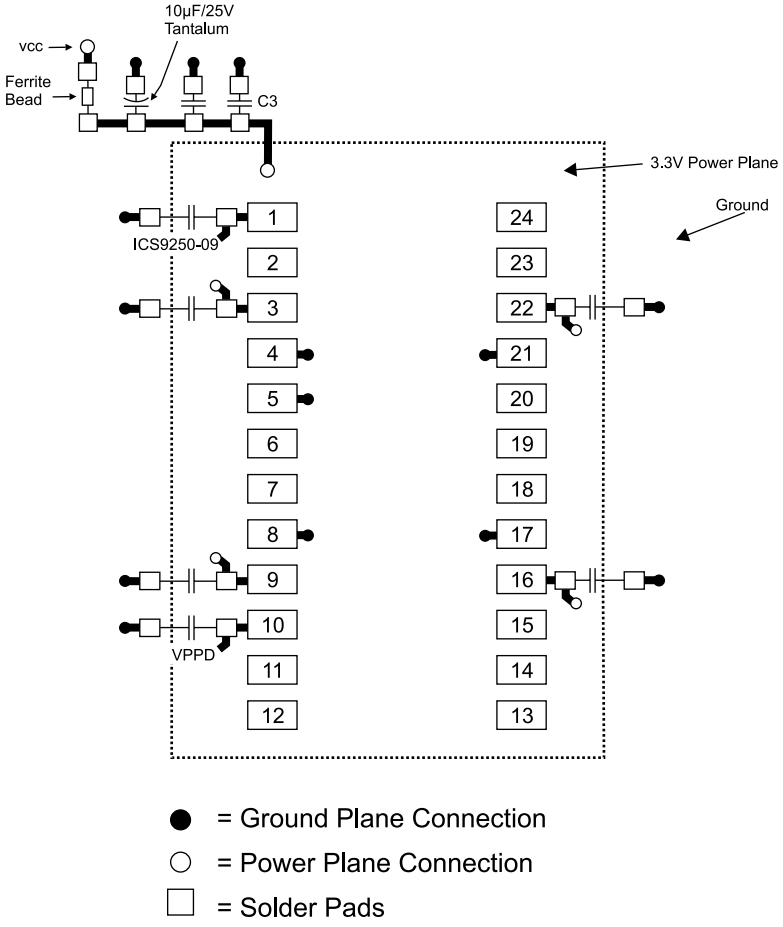
Capacitor Values:

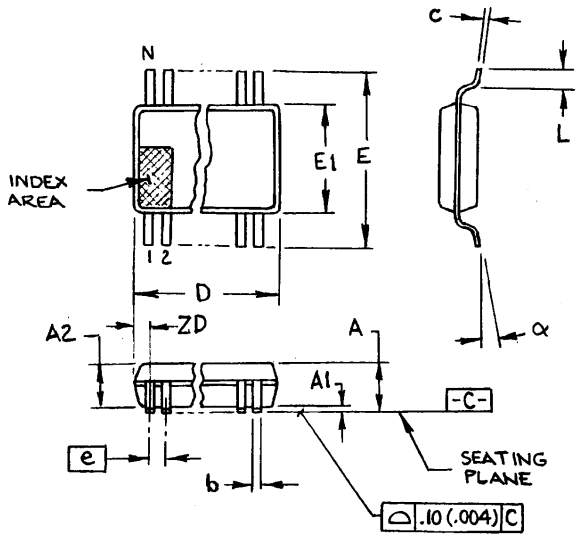
C3 : 100pF ceramic

All unmarked capacitors are 0.01µF ceramic

Connections to VDD:







150 mil SSOP

SYMBOL	In Millimeters COMMON DIMENSIONS		In Inches COMMON DIMENSIONS	
	MIN	MAX	MIN	MAX
A	1.35	1.75	.053	.069
A1	0.10	0.25	.0040	.010
A2	--	1.50	--	.059
b	0.20	0.30	.008	.012
c	0.18	0.25	.007	.010
D	SEE VARIATIONS		SEE VARIATIONS	
E	5.80	6.20	.228	.244
E1	3.80	4.00	.150	.157
e	0.65 BASIC		0.025 BASIC	
L	0.40	1.27	.016	.050
N	SEE VARIATIONS		SEE VARIATIONS	
α	0°	8°	0°	8°
ZD	SEE VARIATIONS		SEE VARIATIONS	

VARIATIONS

N	D mm.		ZD	D (inch)		ZD
	MIN	MAX	(Ref)	MIN	MAX	(Ref)
14	4.80	5.00	0.55	.189	.197	.022
16	4.80	5.00	0.23	.189	.197	.009
18	8.55	8.75	1.80	.337	.344	.071
20	8.55	8.75	1.47	.337	.344	.058
24	8.55	8.75	0.84	.337	.344	.033
28	9.80	10.00	0.84	.386	.394	.033

Ordering Information

ICS9212yF-01-T

Example:

ICS XXXX y F - PPP - T

- **Designation for tape and reel packaging**
- **Pattern Number (2 or 3 digit number for parts with ROM code patterns)**
- **Package Type**
  F=SSOP
- **Revision Designator** (will not correlate with datasheet revision)
- **Device Type (consists of 3 or 4 digit numbers)**
- **Prefix**
  ICS, AV = Standard Device